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**Assembly Note ZZ1**
These assemblies are ESD sensitive, ESD precautions shall be observed.

**Assembly Note ZZ2**
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

**Assembly Note ZZ3**
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

**Assembly Note ZZ4**
Install 'C8' bent over horizontally & apply RTV167 to secure to the PCB surface, bend radius should follow best practice guidelines.

**Assembly Note ZZ5**
'C8' is a non-IPC compliant, custom footprint.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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